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February 25, 2003

Securities and Exchange Commission  
Office of International Corporate Fin  
450 Fifth Street, N.W.  
Washington D.C. 20549



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SUPPL

Re: Samsung Electronics Co., Ltd. – Rule 12g3-2(b) Filing, Commission File No. 82-3109

Ladies and Gentlemen:

The following two announcements were provided by Samsung Electronics Co., Ltd. to the Securities and Exchange Commission pursuant to paragraph (b) (1) (i) of Rule 12g3-2(b) under the Securities Exchange Act of 1934, as amended.

Should you have any questions on the foregoing, please do not hesitate to call Jin Hyuk Park of Simpson Thacher & Bartlett, U.S. counsel to Samsung Electronics Co., Ltd. at (852) 2514-7665. Thank you.

Very truly yours,

Daniel Kim  
Associate  
Investor Relations

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## **Additional Investment in Memory Assembly / Test Equipment**

### **Details**

- SEC will invest in memory assembly and testing equipment to handle the increased production of FABs during the first half of 2003.
- The planned investment is expected to total KRW 104.9 billion, and will be used to put in place more assembly and testing equipment such as wire bonders and testers.

### **Investment Purpose and Effect**

- The investment aims to respond to the increased production of DRAMs and flash memory for mobile devices.

## **Investment in Upgrade and Expansion of Line 5 for SYS.LSI Products**

### **Details**

- SEC will invest in the upgrade and expansion of its SYS.LSI technology in line 5.
- The investment is expected to total KRW 200.2 billion for purchasing equipment and building other necessary facilities.

### **Investment Purpose and Effect**

- As SYS.LSI products are becoming more sophisticated - multifunctional and higher performance- the Company needs to build up its capacity using better design rule.
- The investment is aimed to improve competitiveness in products such as SOC's, smart cards, and image sensors.